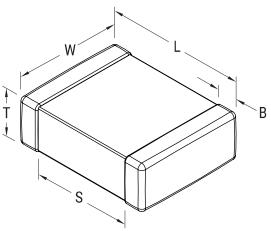


C0603C758DATAC7411

SMD Comm X8G HT150C, Ceramic, 0.75 pF, +/-0.5 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm

SMD Comm X8G HT150C





W	Style	SMD Chip
	Description	SMD, MLCC, High Temperature, Ultra-Stable
В	Features	High Temperature, Ultra-Stable
	RoHS	Yes
	Termination	Tin
	Marking	No
S	AEC-Q200	No
	Typical Component Weight	3.7 mg
Click here for the 3D model.	Shelf Life	78 Weeks
	MSL	1
	Specifications	

General Information

Series

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

Specifications	
Capacitance	0.75 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.5 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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